



# 100% Material Declaration Data Sheet PCG20

PK206 (v1.0) October 5, 2006

Material Declaration Data Sheet

**Average Weight: 0.68104 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.00538</b>	<b>0.79%</b>
	Silicon	7440-21-3	100.00		0.00538	
<b>Die Attach Material</b>					<b>0.00193</b>	<b>0.28%</b>
	Resin	Trade secret	25.00		0.000482	
	Silver	7440-22-4	75.00		0.001445	
<b>Mold Compound</b>					<b>0.47584</b>	<b>69.88%</b>
	Silica	60676-86-0	86.00		0.409223	
	Epoxy Resin (EP)	Trade Secret	7.50		0.035688	
	Carbon black	Trade Secret	0.50		0.002379	
	Epoxy Cresol Novolac	29690-82-2	2.00		0.009517	
	Phenol Resin	Trade Secret	4.00		0.019034	
<b>Leadframe</b>					<b>0.18640</b>	<b>27.37%</b>
	Copper	7440-50-8	97.50		0.181738	
	Iron	7439-89-6	2.35		0.004380	
	Phosphorus	7723-14-0	0.03		0.000056	
	Zinc	7440-66-6	0.12		0.000224	
<b>Leadframe Plating</b>					<b>0.00083</b>	<b>0.12%</b>
	Silver	7440-22-4	100.00		0.00083	
<b>Bond Wire</b>					<b>0.00056</b>	<b>0.08%</b>
	Gold	7440-57-5	100.00		0.00056	
<b>Ext. Plating</b>					<b>0.01010</b>	<b>1.48%</b>
	Tin	7440-31-5	100.00		0.01010	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.